

# Penguin Edge<sup>™</sup> IFC67X1

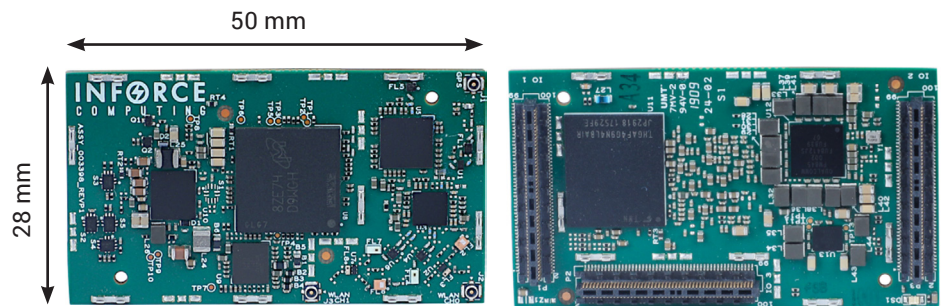
Micro SoM based on the Qualcomm<sup>®</sup> Snapdragon<sup>™</sup> 845 Processor

- ▶ Higher performance with Qualcomm Kryo 385 CPU with independent efficiency and power clusters, each designed to optimize for a unique UX
- ▶ Hexagon 685 DSP and Adreno 630 GPU featuring room-scale 6DoF with SLAM, to support on-device AI and efficient rendering of advanced 3D graphics
- ▶ Dual 14-bit Spectra 280 ISPs support up to 16MP for simultaneous concurrent cameras
- ▶ Qualcomm content protection framework; secure boot; storage and debug security
- ▶ Extended lifecycle; OEM engagement options for build-to-order and custom variants
- ▶ Production-ready with volume-conscious pricing
- ▶ Dedicated technical support from TechWeb

## A compact compute module featuring on-device AI and immersion for embedded applications

The Penguin Edge<sup>™</sup> IFC67X1 Micro SoM is a small compute module that integrates Qualcomm Kryo 385 CPU, Adreno 630 GPU, Hexagon 685 DSP, Spectra 280 camera ISP and Qualcomm's 3rd generation AI-Engine. This enables optimized AI performance for a more responsive, power-efficient user-experience and capture of cinema-grade videos in UHD @ 60fps resolution.

These components, coupled with 2x2 802.11ac Wi-Fi, BT 5.x, a full featured USB-C interface with UHD display capability and high fidelity audio make IFC67X1 Micro SoM a perfect fit for applications that necessitate on-device AI and immersive multimedia experiences. Optional SKUs support extended operating temperature range and EMI shielding for better RF noise protection, while also doubling up as a medium for heat spreading and dissipation to further improve performance.



Embedded AI/ML



Smart Cameras



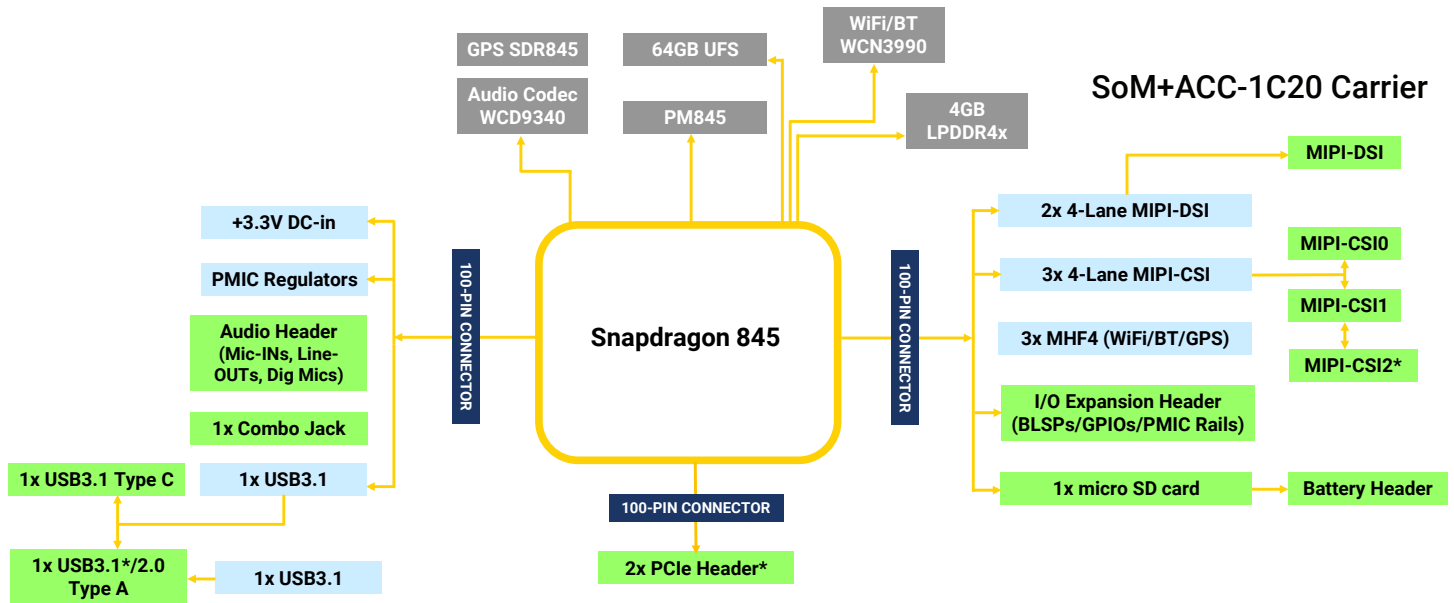
Medical Imaging



Wearable



Digital Signage



\*Features available on IFC67A1 SKU only.

## Processors

- ▶ Custom 64-bit Kryo Octocore ARM V-8 compliant
- ▶ CPU (SDA845 SoC) @ 2.8/1.8GHz each
- ▶ Qualcomm Adreno 630 GPU with support for
- ▶ OpenGL ES 3.2, Vulkan 2 and OpenCL
- ▶ Qualcomm Hexagon 685 DSP with dual-HVX512 for ultra low-power audio processing

## Storage, Multimedia, and Connectivity

- ▶ 4GB LPDDR4 RAM/64GB UFS
- ▶ SD V3.0 µSD card interface
- ▶ 2x USB 3.1 interfaces off which one is USB-C (USB 3.1/ Gen1)
- ▶ DP Alternate Mode on USB-C for 4K-DCI @ 24fps display
- ▶ Concurrent 4K60 10b encode + 4K60 10b decode
- ▶ Dual 4-lane MIPI-CSI lines for HEVC capture @ 4K60
- ▶ 802.11n/ac MU-MIMO WiFi and BT/LE 5.x via WCN3990
- ▶ 1x 1-lane PCIe Gen 2 and 1x 1-lane PCIe Gen 3

## Software

- ▶ Android 10 BSP pre-loaded with Hexagon/SNPE/OpenCV SDKs enabled
- ▶ Debian Linux BSP

## Power, Mechanical, and Environmental

- ▶ Power: +3.8V/6A Input
- ▶ Operating Temp: Commercial grade
- ▶ Relative Humidity: 5 to 95% non-condensing
- ▶ Compliance: RoHS and WEEE
- ▶ Certification: FCC, CE and Japan